

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/26/16569
1.3 Title of PCN	ST Manufacturing Reshaping (MEMS 8_3): For ASIC, Qualification of Singapore for PIX deposition.
1.4 Product Category	Pls refer to the impacted Products List
1.5 Issue date	2026-09-02

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Simone FERRI
2.1.2 Marketing Manager	Tarik SOUBES
2.1.3 Quality Manager	Fabio BIGANZOLI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	ASIC: Singapore for PIX deposition

4. Description of change

	Old	New
4.1 Description	ASIC : CR200 for PIX deposition	ASIC: Singapore for PIX deposition
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

5. Reason / motivation for change

5.1 Motivation	In the frame of ST manufacturing reshaping program, following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing for ASIC, qualification in Singapore for PIX deposition. Please be advised that the dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available. SCHEDULING COMMENT: Below schedule of qualification report availability and intended start of delivery refer to test vehicle qualification.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability of change will be ensured by an internal codification.
-----------------	---

7. Timing / schedule

7.1 Date of qualification results	2026-11-30
7.2 Intended start of delivery	2027-02-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
16569 Public product.pdf 16569 QualPlan Details_MEMS_8_3.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	IIS3DWB10ISTR	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved